

SEMICONDUCTOR DEVICE MANUFACTURING APPARATUS AND METHOD FOR
SUCTIONING MEMBER

ABSTRACT

5 This semiconductor device manufacturing apparatus (10) includes a reference jig (40)
larger than the semiconductor chip (60); and a mounting tool (15) that individually suctions and
transfers the semiconductor chip (60) and the reference jig (40). The mounting tool (15) has: a
base surface (26) that contacts an upper surface of the reference jig (40) when the reference jig
(40) is suction held; and a second block (22) that protrudes from the base surface (26) and has a
10 suction hole (28) formed therein, the second block (22) contacting an upper surface of the
semiconductor chip (60) when the semiconductor chip (60) is suction held. The reference jig
(40) has a receiving recess (46) that receives the second block (22) and forms a closed space
between itself and the mounting tool (15) when suction held by the mounting tool (15).

Representative drawing: FIG. 2